

Reflow Oven for Lead-Free Soldering in the Lab

LPKF ProtoFlow S4

- RoHS-compliant lead-free reflow soldering
- Easy application through integrated user software
- LAN interface for remote operation
- Large inspection window for monitoring the melting process
- Active cooling of process chamber
- Optional additional temperature sensor

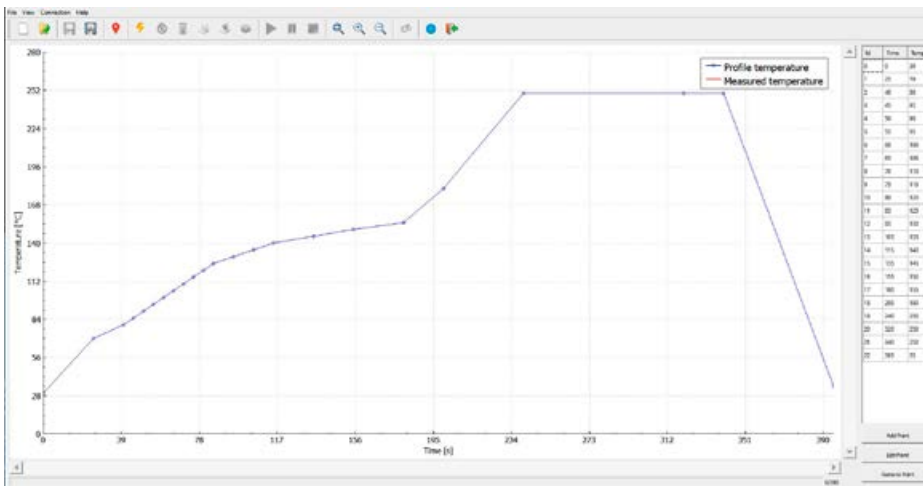


Hot-Air Soldering With Profile

The LPKF ProtoFlow S4 compact hot-air oven is the ideal device for RoHS-compliant lead-free reflow soldering. Visual monitoring of the process is made possible by the large inspection window in the thermally decoupled door. The optimal process parameters for the respective solder can be saved in the integrated software. Apart from predefined process profiles, any custom temperature profiles and process times can be set in the software. They can be saved as custom profiles.

Active cooling at the end of the soldering process with the chamber closed prevents uncontrolled temperature fluctuations in the material. Via an outlet opening, any fumes or gases generated in the process can be safely discharged to an external system.

Four thermocouples ensure perfect heat distribution in the process chamber and regulate the infrared heating elements on the upper and lower sides of the chamber separately. With the help of a freely positionable additional temperature sensor, critical regions right on the PCB can be separately monitored. The low-vibration PCB mount in the process chamber supports processing of double-sided PCB assemblies.



Predefined process temperature profile

LPKF ProtoFlow S4	
Max. PCB size	320 mm x 220 mm (12.6" x 8.6")
Max. reflow temperature	290 °C (554 °F)
Outlet tube for active cooling	Diameter: 80 mm (3.15")
Time for temperature stabilization	<5 min
Ambient temperature	0 – 40 °C (32 – 104 °F)
Power supply	230 V, 50/60 Hz, single-phase 3.5 kW
Dimensions (W x D x H)	555 mm x 480 mm x 300 mm (21.7" x 18.9" x 11.8")
Weight	38 kg (83.8 lbs)
Required software	Windows 10

